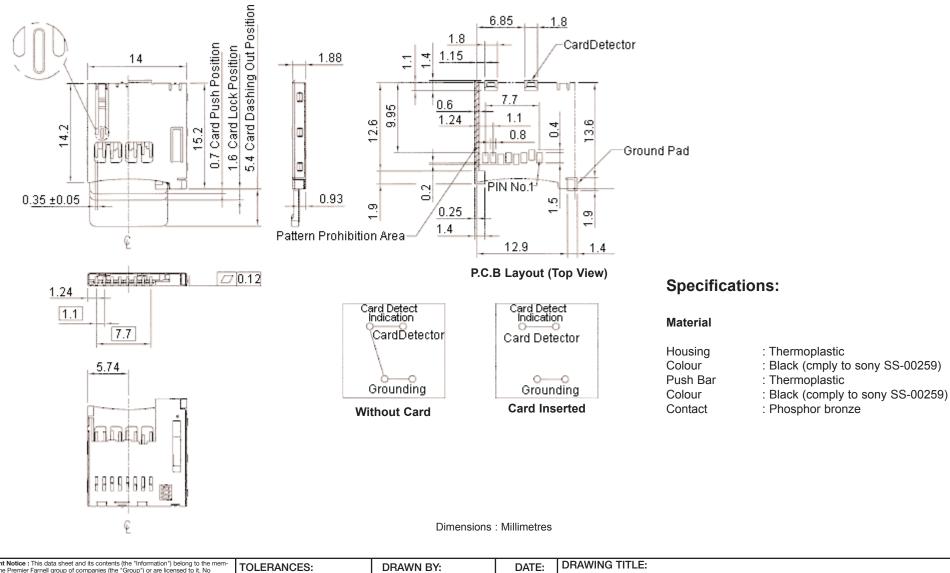
multicomp	PART NO.		REVISIONS									
	TFCMF-20801B0T0-UTE	ECN #	REV	DESCRIPTION	DRAWN	DATE	CHECKD	DATE	APPRVD	DATE		
		-	Α	RELEASED	SID	18/6/12	AMU	18/6/12		02/7/12		



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		CHECKED BY:	DATE:	SIZE	DWG NO.		ELECTRONIC FILE TFCMF-208XXB0TX-UTE-C		REV
		AMU	18/06/12	Δ		M10002588			Α
		APPROVED BY:	DATE:						
ate to limit or restrict the Group's liability for death or personal injury resulting from its negli- gence. Multicomp is the registered trademark of the Group. © Premier Farnell plc 2012.			02/07/12	SCALI	E: NTS	U.O.M.: mm		HEET: 1 OF	- 2

multicomp	PART NO.		REVISIONS									
	TFCMF-20801B0T0-UTE	ECN #	REV	DESCRIPTION	DRAWN	DATE	CHECKD	DATE	APPRVD	DATE		
		-	А	RELEASED	SID	18/6/12	AMU	18/6/12		02/7/12		

Tin 100 μ inches at solder tail, See ordering information for contact Area plating (comply to sony SS-00259) Shell : SUS 304. t=0.15 mm (comply to sony SS-00259)

Within the 0.3 mm high above the shell, It's the function area and please don't do any design for mechanism This product applies to the mechanical specification version 1.0 of Scandisk TransFlash memory module Operating temperature : -25°C to +85°C Storage temperature range : -40°C to +85°C

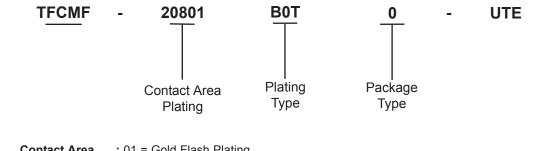
T-Flash

Pin Name 1 DAT2 2 CD / DAT3 3 CMD 4 VDD 5 CLK 6 VSS2 7 DAT0 8 DAT1

Part Number Table

Description	Part Number					
Connector, Micro SD, Memory Card	TFCMF-20801B0T0-UTE					

Part Number Explanation:



Contact Area: 01 = Gold Flash PlatingPlating Type: T = Comply to Sony SS-00259Package Type: 0 = Tray

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	UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE FOR REFERENCE PURPOSES ONLY.	SID	18/06/12	Micro SD, Memory Card					
		CHECKED BY:	DATE:	SIZE DWG NO.		ELECTRONIC FILE	REV		
		AMU	18/06/12	Δ	M10002588	TFCMF-208XXB0TX-UTE-C	Α		
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